

ABSTRACT OF THE DISCLOSURE (FIG. 3)

"COATING APPARATUS"

A coating apparatus comprises a spin chuck for supporting a wafer rotatably, a driving mechanism for rotating the spin chuck, a nozzle for supplying a resist solution or a solvent to the wafer supported by the spin chuck, an outer cup arranged to surround the wafer supported by the spin chuck, an inner cup formed like a ring and arranged along an outer peripheral portion of the wafer to be coated over and in close vicinity of the outer peripheral portion upon coating, and an attaching and detaching mechanism for attaching and detaching the inner cup.

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This Sheet Has Been Replaced

